University of Michigan Department of Electrical Engineering and Computer Science 1301 Beal Ave. Ann Arbor, MI 48109-2122





National Nanotechnology Infrastructure Network

at the University of MICHIGAN



Solid-State Electronics Laboratory

The University of Michigan Solid-State Electronics Laboratory (SSEL) conducts research in electronic, optoelectronic, and micromachined devices, circuits, and microsystems (MEMS). It includes the Michigan Nanofabrication Facility (MNF) a state-of-the-art fabrication facility which serves nationwide researchers.



National Nanotechnology Infrastructure Network

The National Nanotechnology Infrastructure Network (NNIN) is an integrated networked partnership of 13 user facilities, supported by the National Science Foundation since March 1, 2004. The NNIN provides users across the nation open access to leading-edge tools and capabilities to help enable their individual research projects.

The NNIN also has extensive education, training and outreach activities, as well as programs on societal and ethical issues involving nanotechnology.



 Extensive experience with non-traditional users



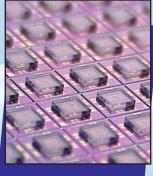
 Silicon processing (including diffusion, LPCVD) Compound semiconductor devices • Thin film deposition Drv etching E-beam lithoaraphy Metrology III-V materials growth

Additional laboratories for:

Why Use MNF?

• 30 years of experience in micro- and nano-fabrication, MEMS and compound semiconductor devices and circuits

 One of the few universities with facilities for both Si integrated circuits and compound semiconductor processing



What the NNIN Brings You

• Quick start up All academic users pay the same rate • Full time staff for tool support and mentoring/training of new users

NNIN pays for technical support and training -Users only pay for lab usage

• IP belongs to user



Facilities

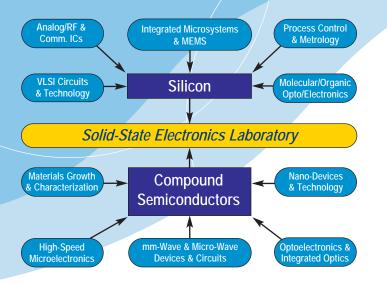
6,000 sq. ft. class 1000/100/10 cleanroom - Open 24/7 Dedicated areas for:

 Packaging Testing



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Research /ctivities



Education and Outreach

Research Experiences

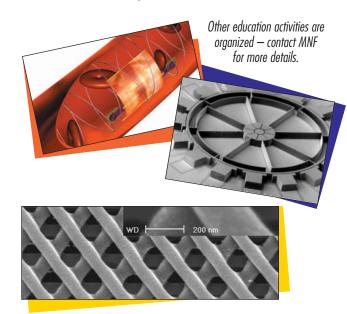
REU (Research Experience for Undergraduates) program during the summer

Courses

College-level web-accessible courses on MEMS and Microsystems Seminar course on Societal Impact of Microsystems

K-12 Outreach

Collaboration with local high schools and middle schools



MNF Equipment and Processes Available to Users

Lithography/Coating

Raith 150 4" ultra-high resolution e-beam lithography and metrology (SEM) tool, minimum feature < 50 nm GCA AC 200 4/6/8" I-line stepper, minimum feature ~ 500 nm ElectroMask II 4" pattern generator, minimum feature ~ 1500 nm EVG 620 4" double-sided contact alianment/lithoaraphy. minimum feature ~ 2um Suss MA/BA 6 4" double-sided contact alignment/lithography, minimum feature ~ 1µm EVG620 bond aligner, minimum feature ~ 2µm Suss MA-45 4" contact alianment/lithography, minimum feature ~ 2um Suss MJB-3 4" contact alignment/lithography, minimum feature ~ 2µm Quintel Q2001 4" contact alignment/lithography, minimum feature ~ 2µm Suss 4" ACS-200 C-to-C coater-developer

Diffusion/Oxidation/Annealing

Thermco 9K 4" auto-load high temperature furnaces, P and B diffusion and drive-in Thermco 9K 4" auto-load high temperature furnaces, thermal oxide (drv and wet) and gate oxide (dry gate) Thermco 9K 4" auto-load high temperature furnaces, anneal/sinter (Si, contacts) JetFirst 150 rapid thermal process tool

LPCVD

Tempress 6604 4/6" auto-load cantilevered high/low temperature furnaces, LTO, HTO, Si3N4, doped polySi, polySi and low stress nitride Thermco 9K 4" auto-load high/low temperature furnaces, LTO, HTO, Si3N4 and polySi

PECVD

SemiGroup dual-chamber, materials: Si₂N4, SiO2 and a-Si. GSI 4/6" single-chamber, materials: DLF, Si₃N₄, SiO2, PSG, BPSG and a-Si

PVD

4" e-beam evaporators (EnerJet, Cooke, SJ-20, SJ-26) for metals (Al, Au, Cr. Pt. Ti, In, Ni, Pd, Sn, Zn, Nb,), Dielectrics (Al₂O₃, SiO₂, SiO, MqO, MqF), compounds (ZnSe), and semiconductors (Ge)

4" sputter coaters (EnerJet, Denton Explorer 14) for metals (Aa, Al, Au, C, Cr, Cu, Ir, Mo, Ta, Ti, Yt, compounds (Al-2% Si, Al-1% Si, ITO, W-10%Ti) and dielectrics (SiO, SiO2, Si3N4)

RIE

Lam 6" 9400-se C-to-C polySi etcher STS 4" high-density ICP deep trench etcher Trion 4" two-chamber C-to-C cluster tool, polySi etcher Plasma/RIE chambers (Technics, March, SemiGroup, PlasmaTherm), polySi, dielectric, III-V. II-VI, polymer, wax, and PR etching

Wet Chemistry

Cleaning (RCA, HF, Piranha) Etching (EDP, KOH, TMAH, HF, HF/NHO_{2}) Organic / Nanofabrication processes Plating (Au, Cu, Pb/Sn, Ni, Ag) Polishina

Wafer Bondina

EVG 501 (anodic, vacuum bond) Suss SB-6 (anodic, Si-Si, fusion, eutectic)



Metrology

Zvao New View 5000 interfrometric surface profilometer Spectrometers (Leitz SP and Nanospec 6100) for thin film measurement DekTak 6M contact surface profilometer JEOL JSM-840 SEM w/Lab 6 cathode Nikon Dual Scope DME (scanning probe and optical microscope)

General Utility

Low temperature bake ovens Tousimis 915B CPD systems for release SCS Labcoter 1 PDS 2010 (parvlene deposition system) Semitool spin rinse drvers Precision hot plates

Wire Bond/Packaging/Test

K&S 4123 wedge bonder Alessi 3200A probe stations Solder reflow

Environmental Test

Environmental chambers (temperature, humidity, autoclaye, vibration analysis, rotation table)

CAD

Layout Circuit simulation

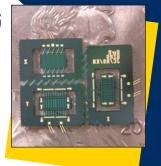
Associated Labs for Additional Capabilities

Electron Microscopy and Analysis Laboratory (EMAL)

IFOL 2010F analytical electron microscope JEOL 3011 high resolution electron microscope FEL Quanta 200 3D dualbeam focused ion beam workstation Diaital Instruments scanning force microscope IIIA Digital Instruments scanning force microscope E (with hystitron triboscope picoindenter), Perkin Elmer / PHI 5400 X-ray photoelectron spectometer FEI Nova NanoLab dualbeam focused ion beam workstation Philips XL30 FEG scanning electron microscope

Michigan Ion Beam Surface Modification and Analysis Laboratory (MIBL)

Tandetron Accelerator 1.7MV (Rutherford backscatter spectrometry, nuclear reaction analysis, elastic recoil detection) Varian Associates CF3000 200kV implanter (5-200kV) Ion beam assisted deposition - IBAD (100-1200eV) Vacuum furnace (up to 1200°C) Buehler nano indenter Sloan Dektak surface profiler





NNIN Personnel at MNF

Prof. Fred Terry NNIN Site Deputy Director

Manaaer Dr. Dennis Grimard MNF Laboratory Manager

Dr. Sandrine Martin NNIN Site Manager

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How to Use MNF

1. Define your goals and needs 2. Contact Sandrine Martin (734-763-6719 or sandrine@umich.edu) to discuss your project



- 3. Fill in necessary forms (see MNF website www.eecs.umich.edu/ssel)
- 4. Start training (online courses available on MNF website)
- 5. Come to Ann Arbor (remote processing is also available limited capabilities only)
- 6. Complete safety and equipment training Work in the lab!

Travel and Accommodations

The Michigan Nanofabrication Facility (MNF) is part of the Electrical Engineering and Computer Science Building (EECS), which is located on North Campus in Ann Arbor.

Ann Arbor is in Southeast Michigan, 45 miles west of Detroit, 240 miles east of Chicago, and 35 miles north of the Ohio state line. It is served by all major airlines through Detroit Metro Airport (25 miles from MNF). Ann Arbor can also be reached from Chicago, Toledo, Cleveland, Pittsburgh by train (Amtrak) or bus (Greyhound).

For all inquiries about the MNF, please contact Dr. Sandrine Martin at 734-763-6719 or sandrine@umich.edu

Prof. Khalil Najafi **NNIN Site Director** MNF Director

Betty Cumminas NNIN Administrative



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